

Field Stop Trench IGBT Die with Sinterable Top Metal

750 V, 225 A

NCG225L75NF8M1

Features

- AEC-Q101 Qualified and PPAP Capable
- Maximum Junction Temperature 175°C
- Advanced FS4 Trench Technology
- Positive Temperature Coefficient
- Easy Paralleling
- Short Circuit Rated
- Very Low Saturation Voltage:
 $V_{CE(SAT)} = 1.45 \text{ V (Typ.) @ } I_C = 225 \text{ A}$
- Optimized for Motor Control Applications
- Emitter Pad Covered with Sinterable Metal Layer

Applications

- Automotive Traction Modules
- General Power Modules

MECHANICAL PARAMETERS

Parameter	Mils	μm
Die Size	394 × 394	10,000 × 10,000
Emitter Pad Size	See chip drawing	See chip drawing
Gate Pad Size	47 × 56	1,200 × 1,430
Scribe Lane Width	3.14	80
Die Thickness	3.4	88
Top Metal	5 μm AlSiCu + 0.95 μm Ti/NiV/Ag (STM)	
Back Metal	0.85 μm Al/NiV/Ag	
Topside Passivation	Silicon Nitride plus Polyimide	
Wafer Diameter	200 mm	
Max Possible Die Per Wafer	226	
Recommended Storage Environment	In original container, in dry nitrogen, < 3 months at an ambient temperature of 23°C	

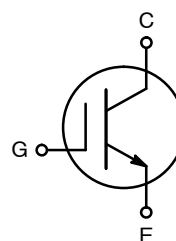


ON Semiconductor®

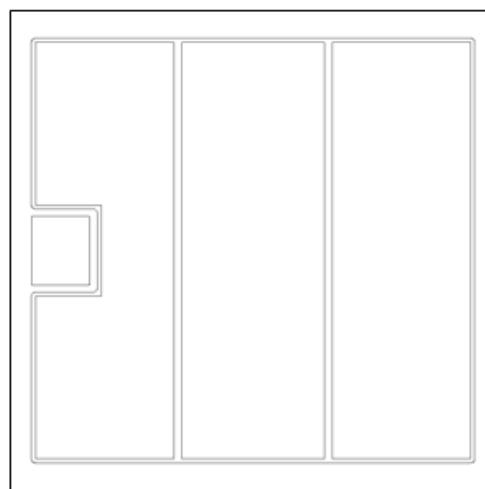
www.onsemi.com

$V_{CES} = 750 \text{ V}$
 $I_C = \text{Limited by } T_{j(max)}$

IGBT DIE



DIODE OUTLINE



ORDERING INFORMATION

Device	Inking?	Shipping
NCG225L75NF8M1	Yes	Sawn Wafer on Tape

NCG225L75NF8M1

ABSOLUTE MAXIMUM RATINGS (T_{VJ} = 25°C unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Collector–Emitter Voltage	V _{CES}	750	V
Gate–Emitter Voltage	V _{GES}	±20	V
DC Collector Current, Limited by T _{VJ} max	I _C	(Note 1)	A
Pulsed Collector Current, V _{GE} = 15 V, tp Limited by T _{VJ} max (Note 2)	I _{CM}	675	A
Short Circuit Withstand Time, V _{GE} = 15 V, V _{CE} ≤ 400 V, T _{VJ} ≤ 175°C	t _{sc}	4	μs
Operating Junction Temperature	T _{VJ}	–40 to +175	°C
Storage Temperature Range	T _{stg}	+18 to +28	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Depends on the thermal properties of assembly.
2. Not subject to production test – verified by design/characterization.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
-----------	--------	-----------------	-----	-----	-----	------

STATIC CHARACTERISTICS (Tested on Wafers)

Collector–Emitter Breakdown Voltage	BV _{CES}	V _{GE} = 0 V, I _C = 1 mA	750	–	–	V
Collector–Emitter Saturation Voltage	V _{CE(SAT)}	I _C = 200 A, V _{GE} = 15 V	–	1.30	1.75	V
Gate–Emitter Threshold Voltage	V _{GE(th)}	V _{GE} = V _{CE} , I _C = 200 mA	4.8	6.0	7.2	V
Collector Cut-off Current	I _{CES}	V _{CE} = V _{CES} , V _{GE} = 0 V	–	–	40	μA
Gate Leakage Current	I _{GES}	V _{GE} = V _{GES} , V _{CE} = 0 V	–	–	±600	nA

ELECTRICAL CHARACTERISTICS (Not Subjected to Production Test – Verified by Design/Characterization)

Collector–Emitter Breakdown Voltage	BV _{CES}	V _{GE} = 0V, I _C = 1 mA	T _{VJ} = –40°C	700	810	–	V
Collector Cut-off Current	I _{CES}	V _{CE} = V _{CES} , V _{GE} = 0 V	T _{VJ} = 150°C	–	0.2	–	mA
			T _{VJ} = 175°C	–	1.5	–	mA
Collector–Emitter Saturation Voltage	V _{CE(SAT)}	I _C = 225 A, V _{GE} = 15 V	T _{VJ} = 150°C	–	1.65	–	V
			T _{VJ} = 175°C	–	1.75	–	V
Input Capacitance	C _{IES}	V _{CE} = 25 V, V _{GE} = 0 V, f = 1 MHz		–	21000	–	pF
Output Capacitance	C _{OES}			–	370	–	pF
Reverse Transfer Capacitance	C _{RES}			–	83	–	pF
Internal Gate Resistance	R _G	f = 1 MHz		–	2.3	–	Ω
Total Gate Charge	Q _{G(Total)}	V _{CE} = 400 V, I _C = 225 A, V _{GE} = –8 V to +15 V		–	690	–	nC
Gate–Emitter Charge	Q _{GE}			–	360	–	nC
Gate–Collector Charge	Q _{GC}			–	158	–	nC
Turn-On Delay Time	t _{d(on)}	V _{CE} = 400 V, I _C = 225 A, R _G = 2 Ω, V _{GE} = +15/–8 V, Inductive Load, T _{VJ} = 25°C		–	104	–	ns
Rise Time	t _r			–	364	–	ns
Turn-Off Delay Time	t _{d(off)}			–	122	–	ns
Fall Time	t _f			–	176	–	ns
Turn-On Delay Time	t _{d(on)}	V _{CE} = 400 V, I _C = 225 A, R _G = 2 Ω, V _{GE} = +15/–8 V, Inductive Load, T _{VJ} = 150°C		–	112	–	ns
Rise Time	t _r			–	356	–	ns
Turn-Off Delay Time	t _{d(off)}			–	130	–	ns
Fall Time	t _f			–	270	–	ns

NCG225L75NF8M1

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise specified) (continued)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
-----------	--------	-----------------	-----	-----	-----	------

ELECTRICAL CHARACTERISTICS (Not Subjected to Production Test – Verified by Design/Characterization)

Turn-On Delay Time	$t_{d(on)}$	$V_{CE} = 400\text{ V}$, $I_C = 225\text{ A}$, $R_G = 2\ \Omega$, $V_{GE} = +15/-8\text{ V}$, Inductive Load, $T_{VJ} = 175^{\circ}\text{C}$	–	112	–	ns
Rise Time	t_r		–	356	–	ns
Turn-Off Delay Time	$t_{d(off)}$		–	136	–	ns
Fall Time	t_f		–	288	–	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Switching characteristics and thermal properties are depending strongly on module design and mounting technology.

For ordering, technique and other information on automotive bare die products from ON Semiconductor, please contact automotivebaredie@onsemi.com

NCG225L75NF8M1

DIE LAYOUT

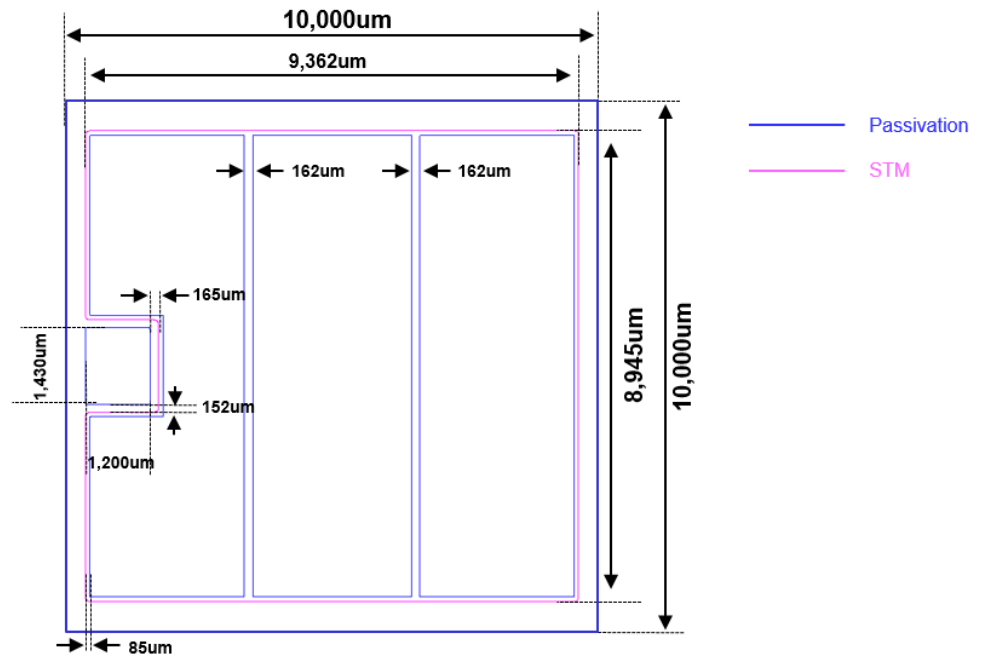


Figure 1. DIE Layout

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales